PRODUCT INFORMATION

HASL refill solder FELDER-ISO-Tin® „HAL-Sn99Ag+-Refill“

Lead-free refill solder for HASL-Applications

HASL solder FELDER-ISO-Tin® „HAL-Sn99Ag+-Refill“
Sn99,7Ag0,3NiGe
according to Fuji-Pat.-No. DE19816671C2, US6179.935, JP3296289

Article no.: 551278...

Application

Refill for existing LEAD-FREE HASL- solder bath “HAL-Sn99Ag+”.

Properties

Beside the well-known advantages of Ni-endowed solders our alloy reaches by adding of silver and germanium improved wetting qualities on copper surfaces in the PCB production and **lowest dross formation** in comparison to all other lead-free solders. A special advantage lies in the extremely low dissolution appearance with copper (in comparison to common SnCu-alloys up to 5 times lower). The low addition of silver of 0,3 % in „Sn99Ag+“ has no negative influence on the corrosion effect on stainless steel parts. Furthermore, this Ag-addition leads in comparison to SnCuNi-alloys, additionally to a lowering of the working temperature and to an improved metal structure of the solder joints.

Metallic composition : 99,7% Sn, 0,3% Ag (+/-0,05)
Endowing: for HASL optimized Ge- and Ni-content
Pb-Contamination: max 0,04%

Melting range/ point : 217 - 222ºC (in the solder bath at 0.7% copper)

Electric conductivity : 7,5m/Ωmm^2

Specific weight : 7,33 g/m^3

Hardness Hv : 14,1

Recommend tinning temp. : 258 - 270ºC (at a Cu-content of 0,7 – 1,1 %)

Delivery form

400 g rods, 400 mm long

Advice

Other alloys are included in our standard delivery programme.

Stand:12/10